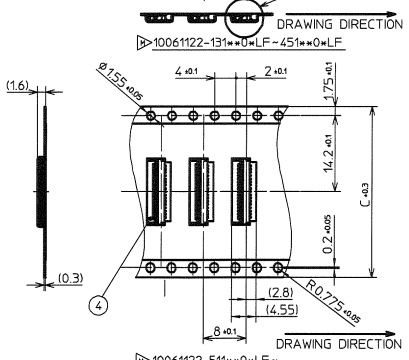
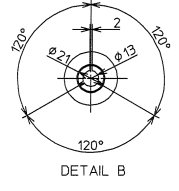
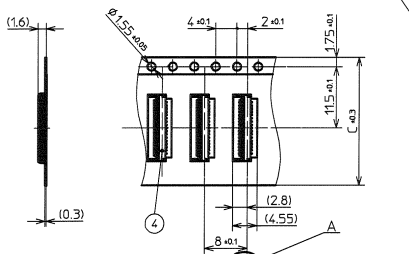
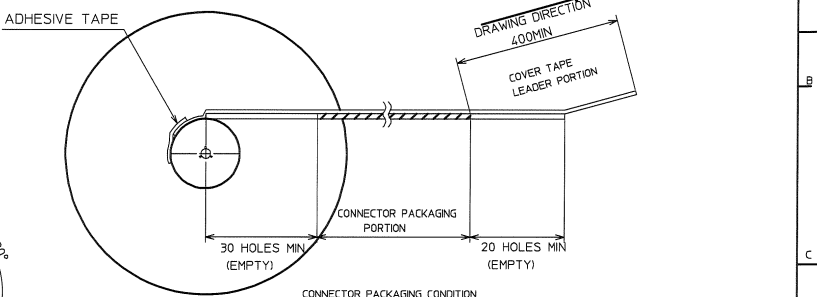
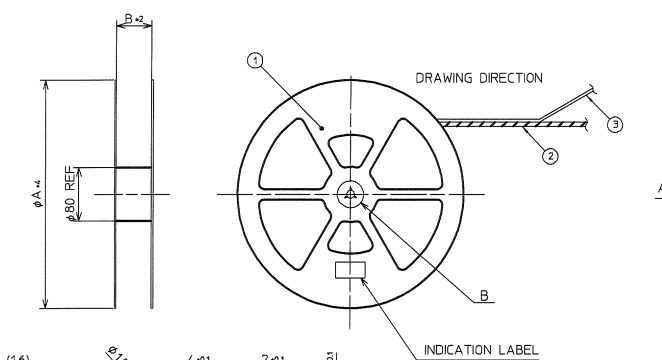


PRODUCT NO
10061122-***1**0*LF

EMBOSS TAPE	DIMENSIONS		
	# A	B	C
10061122-131**0*LF~451**0*LF	330	25.5	24
10061122-511**0*LF~		33.5	32

PT.NO.	PARTS NAME	PRODUCT NO.	MATERIAL	Q'TY	NOTE
1	REEL		POLYSTYRENE	1	COLOR: WHITE/ELECTRIFICATION PREVENTION PROCESSING
2	EMBOSS TAPE		PP OR PET	1	ELECTRIFICATION PREVENTION PROCESSING
3	COVER TAPE		POLYESTER		
4	CONNECTOR	10061122-***1**0*LF	10061122 SHEET2,3		
		10061122-***1**H*LF	10061122 SHEET4,5 6,7	5000	



NOTE
1. THIS ARTICLE CARRIES OUT THE EMBOSS TAPE PACKAGE OF THE P/N 10061122 SERIES CONNECTOR
2. THE SHAPE AND DIMENSION OF THIS ARTICLE ARE BASED ON JIS C 0806 (TAPING OF ELECTRONIC PARTS/SURFACE MOUNTED DEVICE)

- P/N COMPOSITION
- 10061122-***1**0*LF
 - HOUSING MATERIAL 1E: NONE-HALOGEN FREE RESIN 2H: HALOGEN FREE RESIN
 - LEAD FREE
 - PACKAGING FORM: (PLASTIC REEL/EMBOSS TAPE PACKAGE)
 - EMBOSSING TAPE PACKAGE 0: 8mm PITCH
 - PLATING SPEC: (A1 PLATING)
 - MOUNTING 1: SMT/WITH CABLE LOCK 2: SMT/WITHOUT CABLE LOCK 3: SMT/WITH CABLE LOCK/WITH ACTUATOR LOCK 4: SMT/WITHOUT CABLE LOCK/WITH ACTUATOR LOCK
 - CONTACT SIDE 1: DOWN SIDE
 - NO OF POSITION
 - SERIES NAME

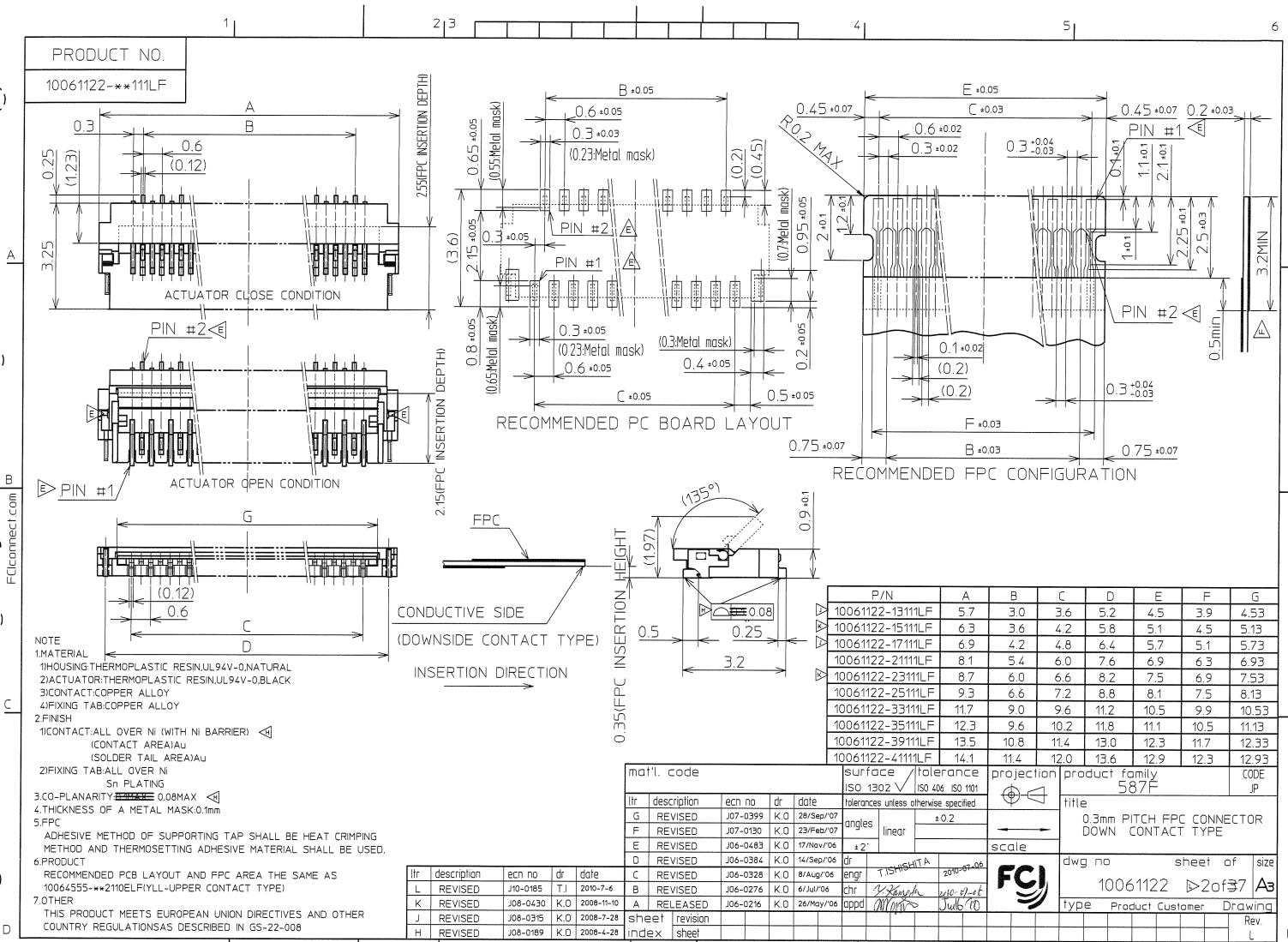
lfr	description	ech no	gr	date	revision	surface	tolerance	projection	product family	code
G	REVISED	27-0399	K.O	28/04/07		ISO 1302	ISO 456 86 90		587F (YLL-D)	
F	REVISED	27-0399	K.O	23/04/07						
E	REVISED	24-0483	K.O	19/04/04						
D	REVISED	24-0384	K.O	14/04/04						
C	REVISED	23-0378	K.O	04/04/04						
B	REVISED	24-0276	K.O	04/04/04						
A	RELEASED	24-0276	K.O	26/04/04						
J	REVISED	208-0296	K.O	2008-7-28						
H	REVISED	208-0289	K.O	2008-4-28						

PDM: Rev:N STATUS: Released Printed: Oct 15, 2010

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PRODUCT NO.

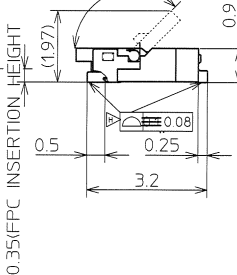
10061122-***111LF



- NOTE
- MATERIAL
 - 1 HOUSING: THERMOPLASTIC RESIN UL94V-0-NATURAL
 - 2 ACTUATOR: THERMOPLASTIC RESIN UL94V-0-BLACK
 - 3 CONTACT: COPPER ALLOY
 - 4 FIXING TAB: COPPER ALLOY
 - FINISH
 - 1 CONTACT: ALL OVER Ni (WITH Ni BARRIER) Δ
 - (CONTACT AREA) Au
 - (SOLDER TAIL AREA) Au
 - 2 FIXING TAB: ALL OVER Ni
 - Sn PLATING
 - CO-PLANARITY ± 0.08 MAX Δ
 - THICKNESS OF A METAL MASK: 0.1mm
 - FPC
 - ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.
 - PRODUCT
 - RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-***2110ELFYLL-UPPER CONTACT TYPE!
 - OTHER
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008

CONDUCTIVE SIDE
(DOWNSIDE CONTACT TYPE)

INSERTION DIRECTION



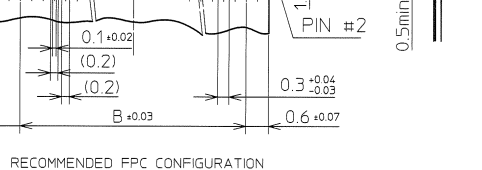
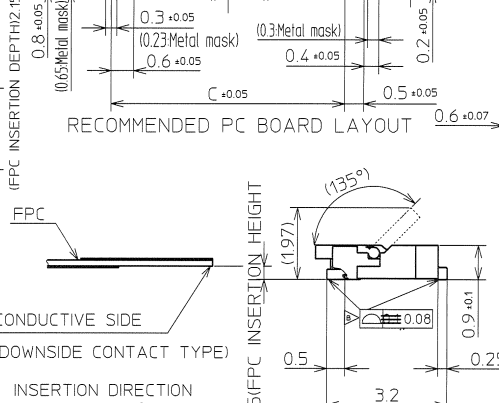
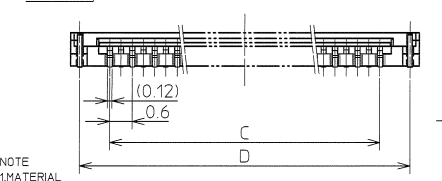
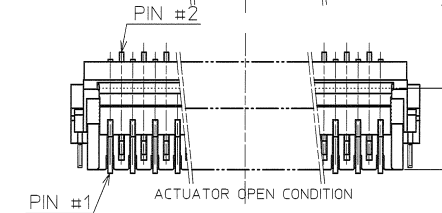
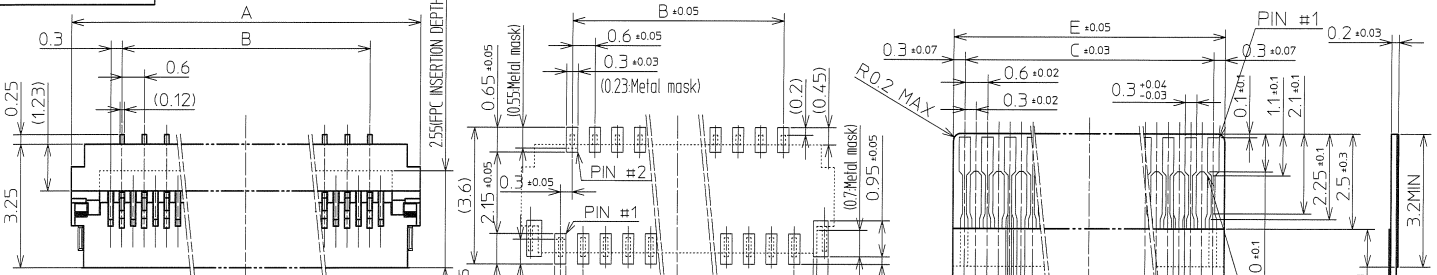
P/N	A	B	C	D	E	F	G
10061122-13111LF	5.7	3.0	3.6	5.2	4.5	3.9	4.53
10061122-15111LF	6.3	3.6	4.2	5.8	5.1	4.5	5.13
10061122-17111LF	6.9	4.2	4.8	6.4	5.7	5.1	5.73
10061122-21111LF	8.1	5.4	6.0	7.6	6.9	6.3	6.93
10061122-23111LF	8.7	6.0	6.6	8.2	7.5	6.9	7.53
10061122-25111LF	9.3	6.6	7.2	8.8	8.1	7.5	8.13
10061122-33111LF	11.7	9.0	9.6	11.2	10.5	9.9	10.53
10061122-35111LF	12.3	9.6	10.2	11.8	11.1	10.5	11.13
10061122-39111LF	13.5	10.8	11.4	13.0	12.3	11.7	12.33
10061122-41111LF	14.1	11.4	12.0	13.6	12.9	12.3	12.93

lir	description	ecn no	dr	date	tolerances unless otherwise specified	projection	scale
G	REVISED	J07-0399	K.O	28/Sep/07	ISO 1302	\oplus	1:1
F	REVISED	J07-0190	K.O	23/Feb/07	angles	\ominus	1:2
E	REVISED	J06-0483	K.O	17/Nov/06	linear	\ominus	1:2
D	REVISED	J06-0384	K.O	14/Sep/06	$\pm 2^\circ$	\ominus	1:1
C	REVISED	J06-0328	K.O	8/Aug/06	ISO 406	\ominus	1:1
B	REVISED	J06-0276	K.O	8/JUL/06	ISO 191	\ominus	1:1
A	RELEASED	J06-0216	K.O	26/May/06	ISO 191	\ominus	1:1

product family	587F	CODE	JP
title	0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE		
dwg no	10061122	sheet of	2 of 3
type	Product	Customer	Drawing

lir	description	ecn no	dr	date	revision
L	REVISED	J10-0185	T.J	2010-7-6	C
K	REVISED	J08-0430	K.O	2008-11-10	B
J	REVISED	J08-0315	K.O	2008-7-28	A
H	REVISED	J08-0189	K.O	2008-4-28	sheet index

PRODUCT NO.
10061122-**-**121LF



- NOTE
- MATERIAL
 - HOUSING: THERMOPLASTIC RESIN UL94V-0-NATURAL
 - ACTUATOR: THERMOPLASTIC RESIN UL94V-0-BLACK
 - CONTACT: COPPER ALLOY
 - FIXING TAB: COPPER ALLOY
 - FINISH
 - 1 CONTACT: ALL OVER Ni (WITH Ni BARRIER) (CONTACT AREA) Au (SOLDER TAIL AREA) Au
 - 2 FIXING TAB: ALL OVER Ni Sn PLATING
 - CO-PLANARITY: 0.08 MAX
 - THICKNESS OF A METAL MASK: 0.1mm
 - FPC
 - ADHESIVE METHOD OF SUPPORTING TAP SHALL BE HEAT CRIMPING METHOD AND THERMOSETTING ADHESIVE MATERIAL SHALL BE USED.
 - PRODUCT
 - RECOMMENDED PCB LAYOUT AND FPC AREA THE SAME AS 10064555-**-**2210ELFYLL-UPPER CONTACT TYPE)
 - OTHER
 - THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008

P/N	A	B	C	D	E
10061122-15121LF	6.3	3.6	4.2	5.8	4.8
10061122-21121LF	8.1	5.4	6.0	7.6	6.6
10061122-23121LF	8.7	6.0	6.6	8.2	7.2
10061122-25121LF	9.5	6.6	7.2	8.8	7.8
10061122-33121LF	11.7	9.0	9.6	11.2	10.2
10061122-35121LF	12.3	9.6	10.2	11.8	10.8
10061122-37121LF	12.9	10.2	10.8	12.4	11.4
10061122-39121LF	13.5	10.8	11.4	13.0	12.0
10061122-41121LF	14.1	11.4	12.0	13.6	12.6
10061122-43121LF	14.7	12.0	12.6	14.2	13.2
10061122-45121LF	15.3	12.6	13.2	14.8	13.8

mat'l. code	surface	tolerance	projection	product family	CODE
lir description	ISO 1302	ISO 406 ISO 1101	MM	587F	JP
ecn no	dr	date	angles	linear	±0.2
E REVISED	J10-0185	T.I	2010-7-6		
D REVISED	J10-0073	T.I	2010-5-17	dr	
C REVISED	J08-0430	K.O	2008-11-10	engr	
B REVISED	J08-0189	K.O	2008-4-28	chr	
A RELEASED	J07-0399	K.O	28/Sep/07	appd	

title
0.3mm PITCH FPC CONNECTOR
DOWN CONTACT TYPE

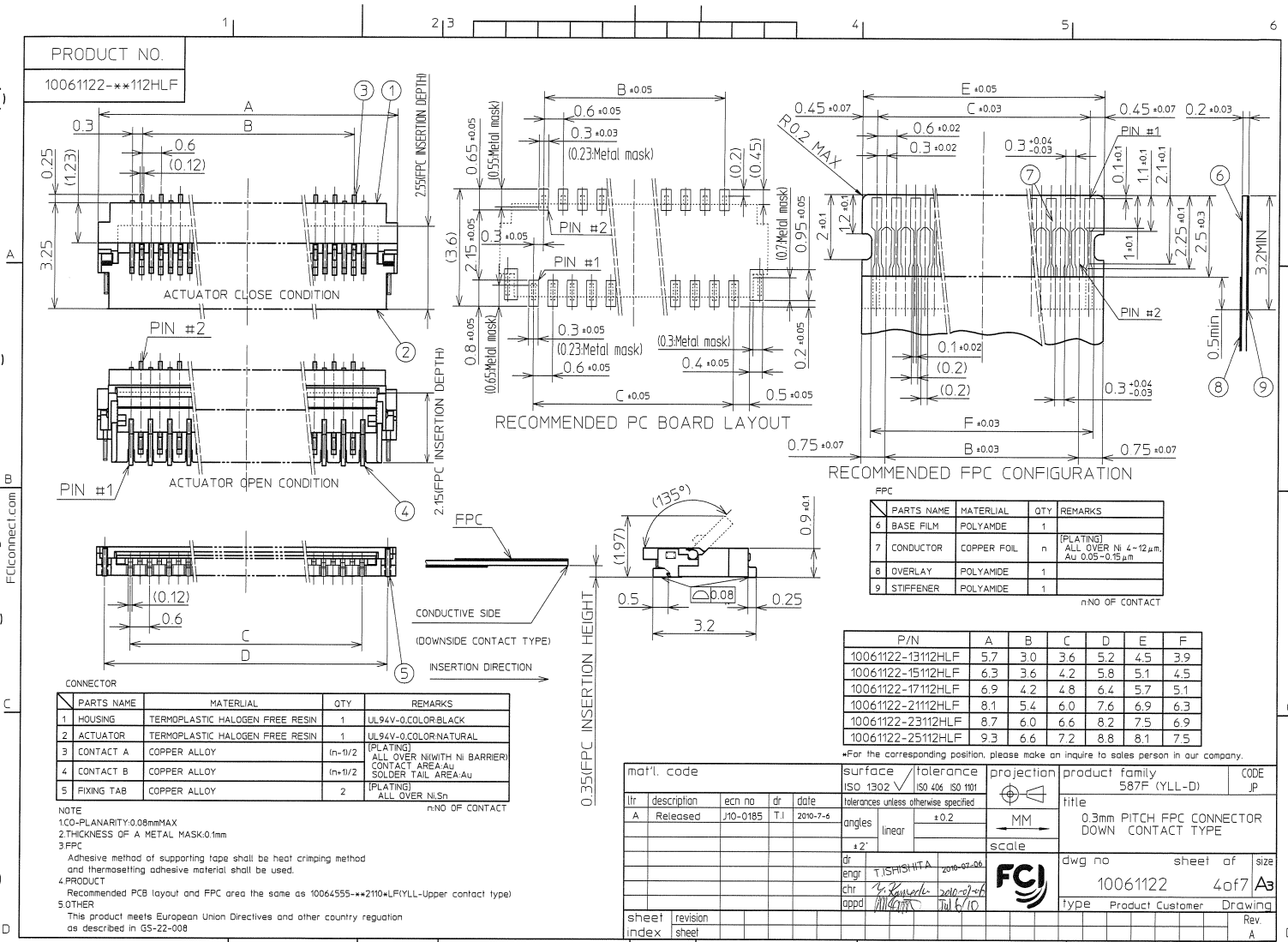
dwg no 10061122 sheet of 3 of 7 size A3

type Product Customer Drawing

Rev E

PRODUCT NO.

10061122-**-112HLF



PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA: Au SOLDER TAIL AREA: Au
4 CONTACT B	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni:Sn
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni:Sn

NOTE
 1.CO-PLANARITY:0.08mmMAX
 2.THICKNESS OF A METAL MASK:0.1mm
 3.FPC
 Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.
 4.PRODUCT
 Recommended PCB layout and FPC area the same as 10064555-**-2110-LF(YLL-Upper contact type)
 5.OTHER
 This product meets European Union Directives and other country regulation as described in GS-22-008

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOL	n	[PLATING] ALL OVER Ni 4~12µm, Au: 0.05~0.15µm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT

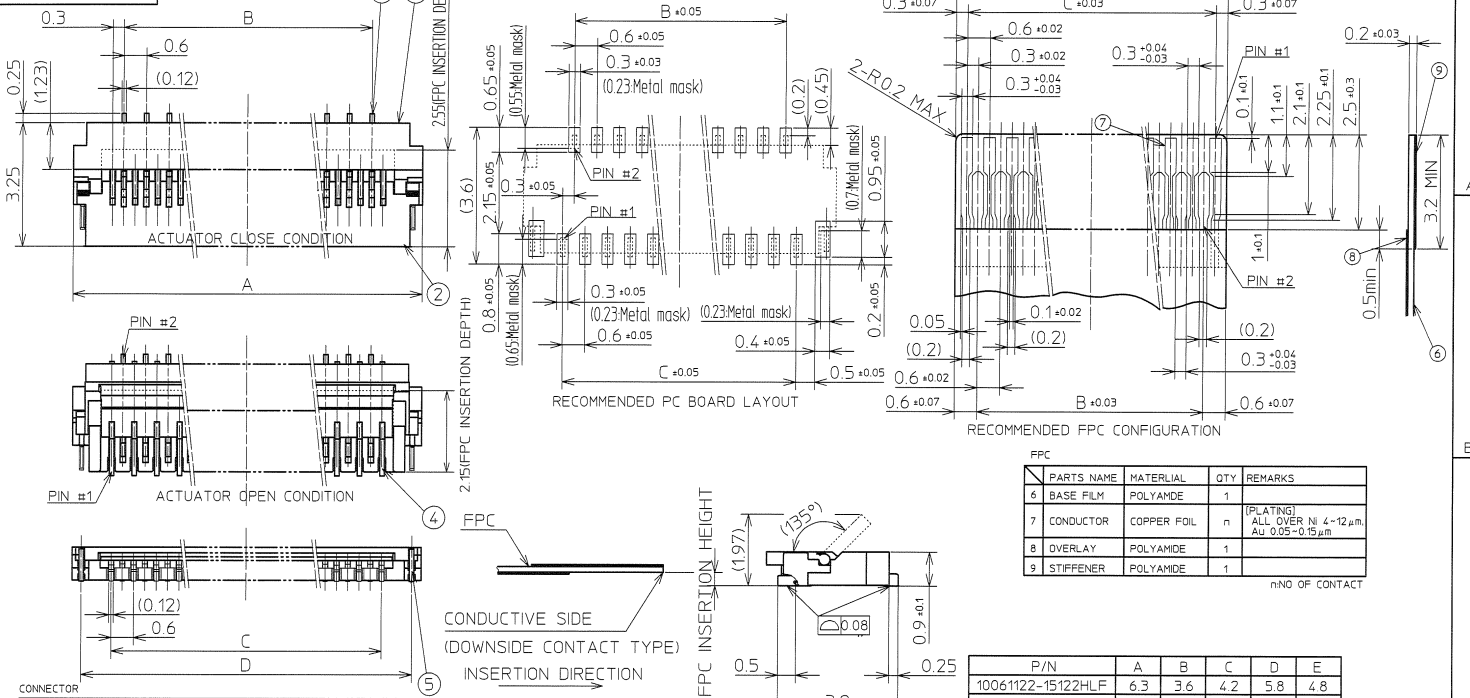
P/N	A	B	C	D	E	F
10061122-13112HLF	5.7	3.0	3.6	5.2	4.5	3.9
10061122-15112HLF	6.3	3.6	4.2	5.8	5.1	4.5
10061122-17112HLF	6.9	4.2	4.8	6.4	5.7	5.1
10061122-21112HLF	8.1	5.4	6.0	7.6	6.9	6.3
10061122-23112HLF	8.7	6.0	6.6	8.2	7.5	6.9
10061122-25112HLF	9.3	6.6	7.2	8.8	8.1	7.5

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code	surface	tolerance	projection	product family	CODE
	ISO 1302	ISO 406 ISO 101		587F (YLL-D)	JP
lir description	sec no	dr date	tolerances unless otherwise specified	title	
A Released	J10-0185	T.I	2010-7-6	0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE	
angles	linear	scale		dwg no	sheet of
				10061122	4 of 7
dr	enr	chr	appd	type	Product Customer Drawing
	T. ISHII			Rev	A

PRODUCT NO

10061122-**122HLF



PARTS NAME	MATERIAL	QTY	REMARKS
6	BASE FILM	POLYAMIDE	1
7	CONDUCTOR	COPPER FOIL	n (PLATING) ALL OVER Ni 4-12 μm. Au 0.05-0.15 μm
8	OVERLAY	POLYAMIDE	1
9	STIFFENER	POLYAMIDE	1

n=NO OF CONTACT

PARTS NAME	MATERIAL	QTY	REMARKS
1	HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1 UL94V-0.COLOR:BLACK
2	ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1 UL94V-0.COLOR:NATURAL
3	CONTACT A	COPPER ALLOY	(n-1)/2 (PLATING) ALL OVER Ni WITH Ni BARRIER. CONTACT AREA: Au SOLDER TAIL AREA: Au
4	CONTACT B	COPPER ALLOY	(n-1)/2
5	FIXING TAB	COPPER ALLOY	2 (PLATING) ALL OVER Ni Sn

n=NO OF CONTACT

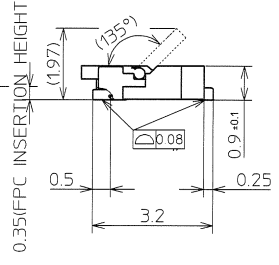
NOTE

- 1.CO-PLANARITY:0.08mmMAX
- 2.THICKNESS OF A METAL MASK:0.1mm
- 3.FPC

Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.

4.PRODUCT Recommended PCB layout and FPC area the same as 10064555-**2110-LF(YLL-Upper contact type)

5.OTHER This product meets European Union Directives and other country regulation as described in GS-22-008



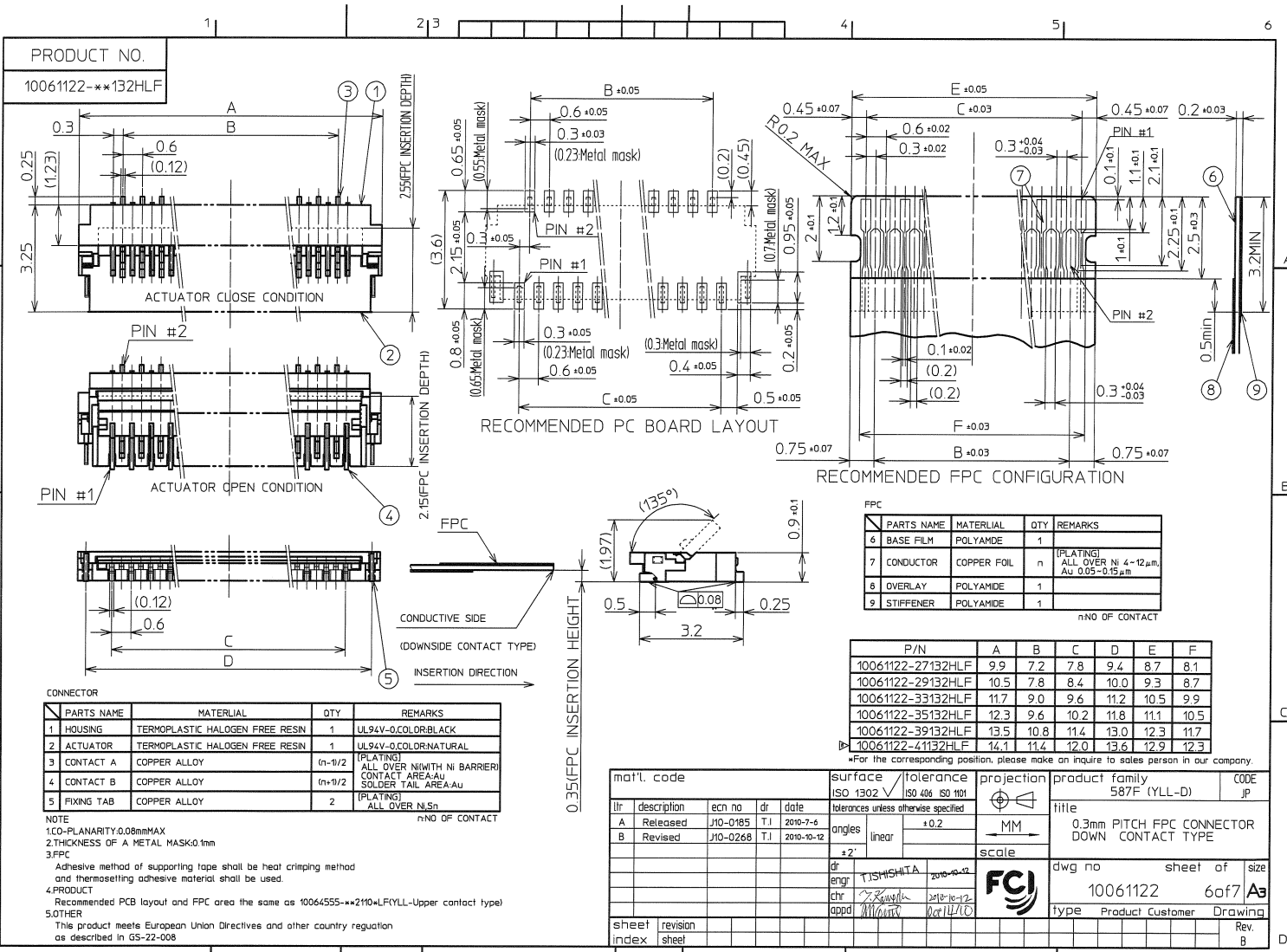
P/N	A	B	C	D	E
10061122-15122HLF	6.3	3.6	4.2	5.8	4.8
10061122-21122HLF	8.1	5.4	6.0	7.6	6.6
10061122-23122HLF	8.7	6.0	6.6	8.2	7.2
10061122-25122HLF	9.3	6.6	7.2	8.8	7.8

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code	surface ISO 1302 ✓	tolerance ISO 406 ISO 1101	projection	product family 587F (YLL-D)	CODE JP
lfr description	ecn no	dr date	angles	title	
A Released	J10-0185	T.J 2010-7-6	linear ± 0.2	0.3mm PITCH FFC CONNECTOR DOWN CONTACT TYPE	
			± 2°		
			scale	dwg no	sheet of
			MM	10061122	5 of 7
dr				type	Product Customer Drawing
enrg T.ISHIYAMA					
chr					
appd					
sheet index	revision sheet				Rev. A

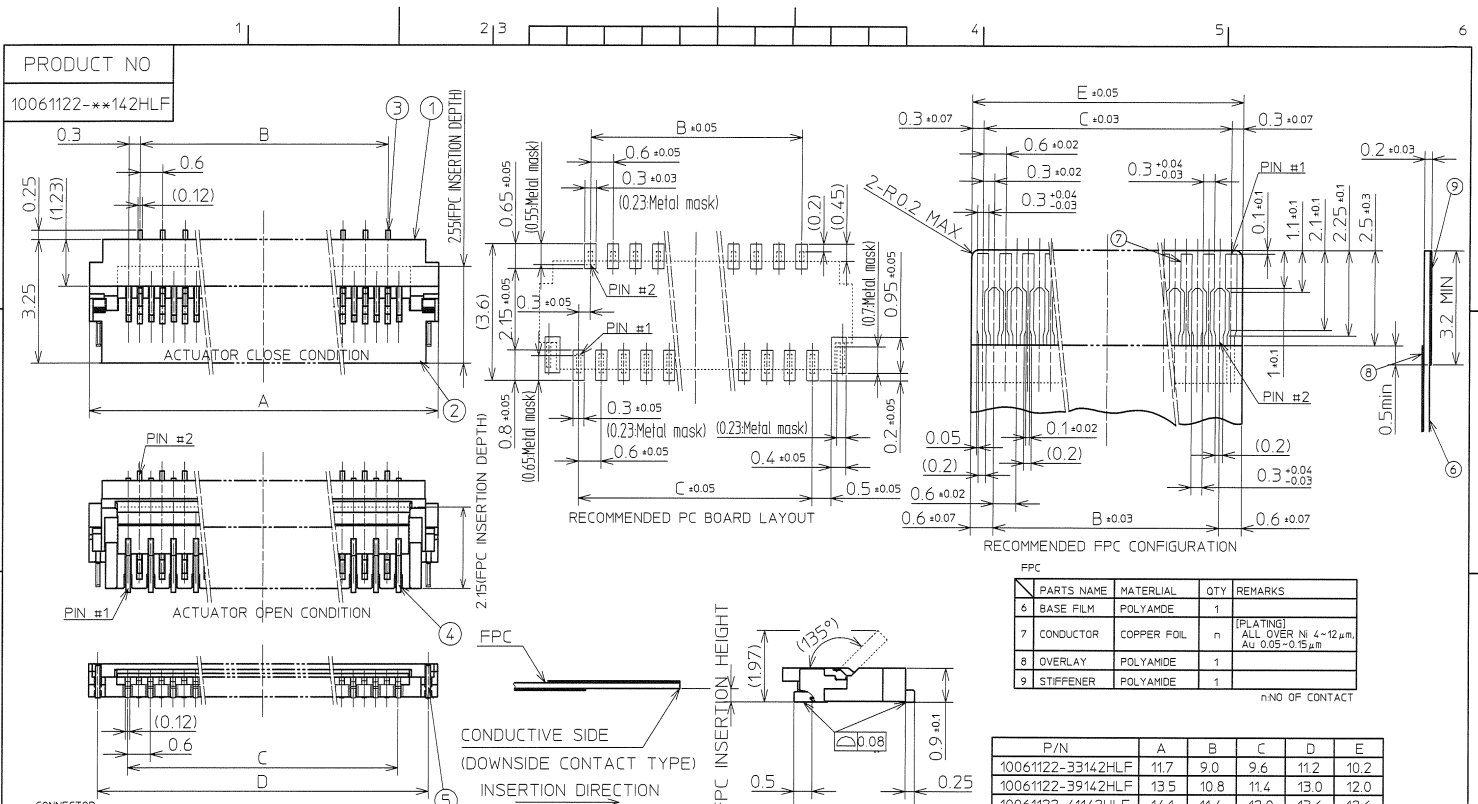
PDM: Rev:N STATUS:Released Printed: Oct 15, 2010

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PRODUCT NO

10061122-**-**142HLF



PARTS NAME	MATERIAL	QTY	REMARKS
1 HOUSING	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:BLACK
2 ACTUATOR	TERMOPLASTIC HALOGEN FREE RESIN	1	UL94V-0.COLOR:NATURAL
3 CONTACT A	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA Au SOLDER TAIL AREA Au
4 CONTACT B	COPPER ALLOY	(n-1)/2	[PLATING] ALL OVER Ni(WITH Ni BARRIER) CONTACT AREA Au SOLDER TAIL AREA Au
5 FIXING TAB	COPPER ALLOY	2	[PLATING] ALL OVER Ni Sn

NOTE

1.CO-PLANARITY:0.08mmMAX
 2.THICKNESS OF A METAL MASK:0.1mm
 3.FPC
 Adhesive method of supporting tape shall be heat crimping method and thermosetting adhesive material shall be used.
 4.PRODUCT Recommended PCB layout and FPC area the same as 10064555-**-**2110-MLF(YLL-Upper contact type)
 5.OTHER This product meets European Union Directives and other country regulation as described in GS-22-008

PARTS NAME	MATERIAL	QTY	REMARKS
6 BASE FILM	POLYAMIDE	1	
7 CONDUCTOR	COPPER FOIL	n	[PLATING] ALL OVER Ni (4~12µm) Au 0.05~0.15µm
8 OVERLAY	POLYAMIDE	1	
9 STIFFENER	POLYAMIDE	1	

n: NO OF CONTACT

P/N	A	B	C	D	E
10061122-33142HLF	11.7	9.0	9.6	11.2	10.2
10061122-39142HLF	13.5	10.8	11.4	13.0	12.0
10061122-41142HLF	14.1	11.4	12.0	13.6	12.6
10061122-43142HLF	14.7	12.0	12.6	14.2	13.2
10061122-45142HLF	15.3	12.6	13.2	14.8	13.8
10061122-51142HLF	17.1	14.4	15.0	16.6	15.6

*For the corresponding position, please make an inquire to sales person in our company.

mat'l. code	surface ISO 1302 ✓ tolerance ISO 406 ISO 1101	projection	product family	CODE
dr description	ecn no	dr date	587F (YLL-D)	P
A Released	J10-0185	TJ 2010-7-6	title	0.3mm PITCH FPC CONNECTOR DOWN CONTACT TYPE
angles	linear	± 0.2	scale	MM
dr engr	TISHISHITA	2010.07.06	dwg no	10061122
chr			sheet of	7 of 7
appd			size	A3
sheet index	revision sheet		type	Product Customer Drawing
			Rev.	A